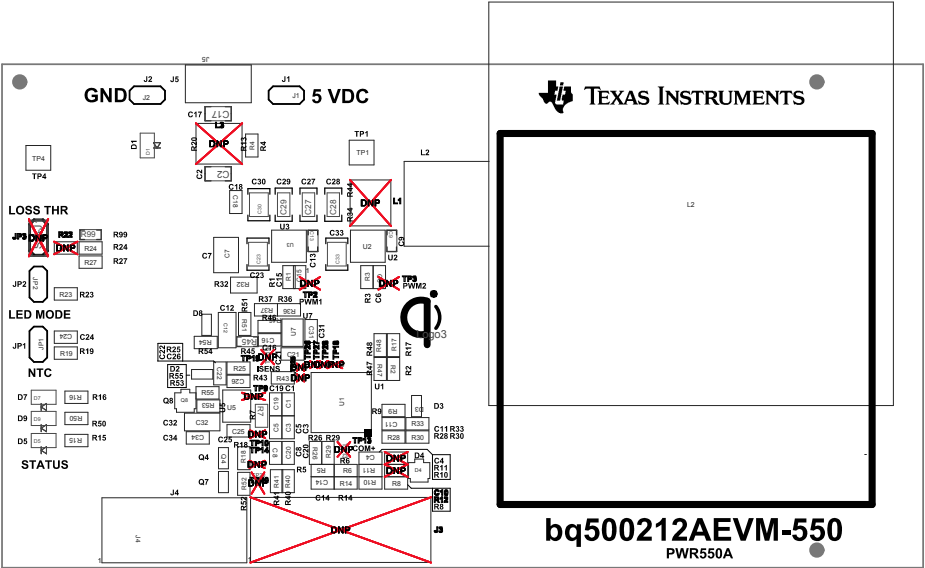


- Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1
- These assemblies are ESD sensitive, ESD precautions shall be observed.
- These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.
- Wurth Elektronik (P/N 760-308-111) www.we-online.de (Oliver Optitz, Oliver.Optitz@we-online.de)
- If part number GP1500-0.020-00-0404 is used the Sil-Pads need to be cut into 2 inch squares.
- Solder Coil leads to plated through holes near TP1 and TP2
- Apply thin layer of SA-1000 between Aluminum Plate MCH003 and PCB during installation
- See PWR045 Assembly Guide for build up on L2 and associated hardware
- Label will have the following: CE Mark (min 5 mm, in proper proportion) This ISM device complies with Part 18 of the FCC Rule.This ISM device complies with Canadian ICES-001. Cet appareil ISM est conforme à la norme NMB-001 du Canada.

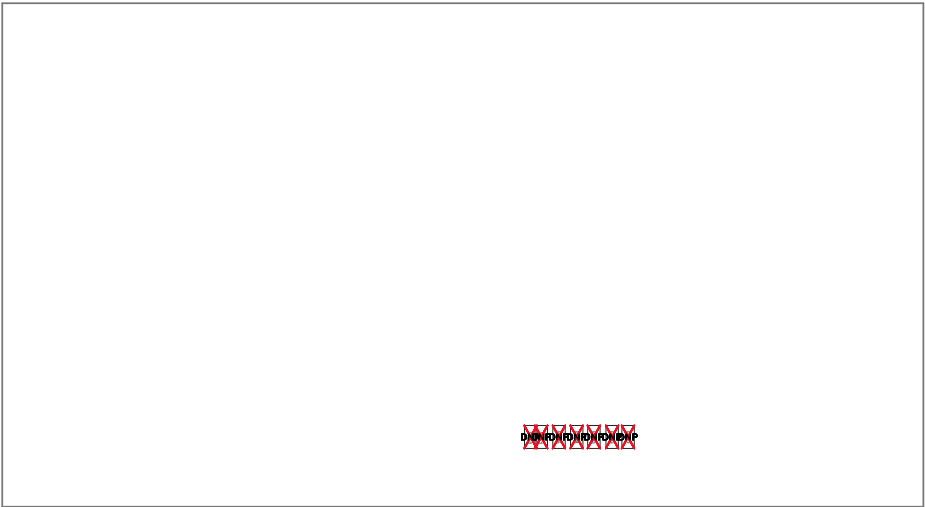


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: 001

TABLE 1

Variant	Label text
001	ChangeMe!
002	ChangeMe!

PCB VIEWED FROM TOP SIDE	BOARD #: PR550	REV: A	SVN REV: Not In VersionControl
IGNORE -> Top Board Outline			
PLOT NAME = Top Assembly Drawing	GENERATED : 9/13/2013 8:57:31 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PR550	REV: A	SVN REV: Not In VersionControl
	IGNORE -> μsIɹev0 ɹoʃɹoθ		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 9/13/2013 8:57:32 AM	TEXAS INSTRUMENTS	

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